

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|---|---|------------------|---------|------------------|
| L1 | 20402 | 438/618,622,633,637,638,692,552,662,663,672,675,677,698,679,700,704-706,714,725.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 13:46 |
| L2 | 1243 | L1 and ((therm\$4 temperatur\$3 heat\$3) with (decompos\$4 decomposit\$3 destro\$3 wast\$3 consum\$3 absorb\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 16:50 |
| L3 | 1045 | 2 and (embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried hollow hole cave) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 13:47 |
| L4 | 759 | 2 and ((embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried hollow concave cave hole) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 16:52 |
| L5 | 757 | 4 and (plug contact\$3 \$5connect\$4 \$5conduct\$3) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 13:52 |
| L6 | 757 | 4 and (plug \$5contact\$3 \$5connect\$4 \$5conduct\$3) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 16:53 |
| L7 | 25 | (US-20060128089-\$ or US-20050179135-\$ or US-20050124168-\$ or US-20050151256-\$ or US-20050272248-\$ or US-20030205817-\$ or US-20050042874-\$ or US-20050079705-\$ or US-20040099951-\$).did. or (US-6821896-\$ or US-6440842-\$ or US-6174804-\$ or US-6033977-\$ or US-6309957-\$ or US-6803669-\$ or US-6949456-\$ or US-6358849-\$ or US-6596624-\$ or US-7211496-\$ or US-6171971-\$ or US-6898851-\$ or US-6800551-\$ or US-6664181-\$ or US-6514671-\$ or US-6440838-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/09/27 14:53 |
| L8 | 673 | 6 and ((remov\$3 etch\$3) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 15:45 |
| L9 | 518 | 8 and ((embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried hollow concave cave hole) near3 (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 15:01 |
| L10 | 86 | 9 and project\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 15:03 |
| L11 | 2 | 9 and (trip\$3 near2 shape\$3) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 15:03 |
| L12 | 247 | 9 and (dielectric insulat\$3 \$5mask\$5 sacrificial\$3) near2 (region portion) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 15:05 |

EAST Search History

| | | | | | | |
|-----|-------|---|---|----|----|------------------|
| L13 | 13 | ("20020028575" "20020098677" "20030064577" "20040063305" "20050037604" "5798559" "6255712" "6440838" "6440861" "6780753" "6815329" "6841844").PN. OR ("6949456").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/27 15:10 |
| L14 | 7 | ("6033977" "6174804" "6284641" "6309957").PN. OR ("6440842").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/27 15:23 |
| L15 | 72 | ("4523372" "5158910" "5422309" "5529953" "5602423" "5614765" "5705430" "5710061" "5801099").PN. OR ("6033977").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/27 15:28 |
| L16 | 190 | 12 not (7 10 11 13 14 15) | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/27 16:06 |
| L19 | 180 | 16 and ((remov\$3 etch\$3) near4 (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 16:55 |
| L20 | 1570 | 438/618.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 15:59 |
| L21 | 3056 | 438/637.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 15:47 |
| L22 | 10 | 12 not (7 10 11 13 14 15 19) | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/27 16:54 |
| L23 | 763 | 438/666.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/27 16:49 |
| L24 | 3308 | 257/e21.579.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 16:44 |
| L25 | 26856 | ((therm\$4 temperatur\$3 heat\$3) near3 (decompos\$4 decompisit\$3 destro\$3 wast\$3 consum\$3 absorb\$3)) and ((embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried hollow concave cave hole) near4 (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 16:58 |
| L26 | 25358 | 25 and (plug \$5contact\$3 \$5connect\$4 \$5conduct\$3) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 17:57 |
| L27 | 24848 | 26 not (7 10 11 13 14 15 19 22) | US-PGPUB; USPAT; USOCR | OR | ON | 2007/09/27 16:55 |
| L28 | 8303 | 27 and ((therm\$4 temperatur\$3 heat\$3) with (decompos\$4 decompisit\$3 destro\$3 wast\$3 consum\$3 absorb\$3) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 16:57 |
| L29 | 4147 | 28 and ((therm\$4 temperatur\$3 heat\$3) with (decompos\$4 decompisit\$3) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 18:01 |

EAST Search History

| | | | | | | |
|-----|------|---|---|----|----|------------------|
| L30 | 670 | 29 and project\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 17:02 |
| L31 | 4043 | 29 and ((therm\$4 temperatur\$3 heat\$3) near3 (decompos\$4 decomposit\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 17:03 |
| L32 | 642 | 30 and 31 | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 17:04 |
| L33 | 556 | 32 and (@ad<"20050612" @rlad<"20050615") | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 17:04 |
| L34 | 325 | 33 and ((plug \$5contact\$3 \$5connect\$4 \$5conduct\$3) near4 (hole trench open\$3 via strip\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 17:09 |
| L35 | 4649 | ((plug \$5contact\$3 \$5connect\$4 \$5conduct\$3) and ((therm\$4 temperatur\$3 heat\$3) near3 (decompos\$4 decomposit\$3))). clm. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 18:00 |
| L36 | 475 | 35 and ((remov\$3 etch\$3) near5 (thermal\$3 thermo\$4 heat\$3 temperat\$3)).clm. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 17:59 |
| L37 | 169 | 36 and (\$4silicon semiconduct\$3).clm. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 18:00 |
| L38 | 38 | 37 and (((therm\$4 temperatur\$3 heat\$3) with (decompos\$4 decomposit\$3) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3))))).clm. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 18:02 |

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| S1 | 55 | "6033977" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2007/05/30 15:18 |
| S2 | 44 | S1 and ((dielectric insulat\$4 organic \$2oxide) same (via recess open\$3 groov\$3 trench\$3 gap\$3 slot\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:10 |
| S3 | 43 | S2 and (remov\$4 heat\$4 temperatur\$4 therm\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/25 16:31 |
| S4 | 1 | 10/539280 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/25 16:31 |
| S5 | 4 | ("6033977" "6174804" "6284641" "6309957").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/09/25 16:37 |
| S6 | 49 | ("5766446" "5475567" "5508881" "5625528" "5741721" "5889449" "6128178" "4266263" "4370697" "4373782" "4828346" "4837534" "4870319" "5012319" "5200855" "5381149" "5471221" "5472886" "5488199" "5742002" "5748358" "5893967" "5909261" "5936493" "5978157").pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 14:01 |
| S7 | 5 | S6 and ((organic \$2oxide \$nitride) same (remov\$4 burn\$4 melt\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 12:12 |
| S8 | 7 | S6 and ((organic \$2oxide \$nitride) same (heat\$4 temperatur\$4 therm\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 12:19 |
| S9 | 3 | Hoang-viet-nguyen.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 14:04 |
| S10 | 9 | Nguyen-hoang-viet.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 14:09 |
| S11 | 7 | gravesteijn-dirk-jan.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 14:05 |

EAST Search History

| | | | | | | |
|-----|-------|---|---|----|----|------------------|
| S12 | 1 | hoofman-romano-julma-oscar-maria.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 14:03 |
| S13 | 0 | Nguyen-viet-hoang.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 14:04 |
| S14 | 2729 | 438/637.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:02 |
| S15 | 2792 | 438/622.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 14:49 |
| S16 | 14538 | 257/296,741,750,774,e21.553,e21.579,e21.585,e21.587,e21.589,e23.145.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:04 |
| S17 | 831 | H01L21/4763.ipc. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:05 |
| S18 | 774 | H01L21/302.ipc. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:06 |
| S19 | 1996 | (S16 S17 S18) and (organic same (heat\$4 therm\$4 temperatur\$4 melt\$4 vapor\$6 evaporat\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:11 |
| S20 | 1808 | S19 and ((dielectric insulat\$4 organic \$2oxide) same (via recess open\$3 groov\$3 trench\$3 gap\$3 slot\$3 plug)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:10 |
| S21 | 1535 | S20 and (organic same (temperatur\$4 melt\$4 vapor\$6 evaporat\$4 decompos\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:12 |
| S22 | 880 | S21 and (organic with (temperatur\$4 melt\$4 vapor\$6 evaporat\$4 decompos\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:16 |

EAST Search History

| | | | | | | |
|-----|------|--|---|----|----|------------------|
| S23 | 421 | S21 and (organic with (temperatur\$4 melt\$4 vapor\$6 evaporat\$4 decompos\$4) with (larg\$3 high\$4 low\$4 small\$3 above below)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:14 |
| S24 | 280 | S23 and (organic with (temperatur\$4 heat\$4 therm\$4) with (larg\$3 high\$4 low\$4 small\$3 above below)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 15:14 |
| S25 | 100 | S24 and (organic with (temperatur\$4 heat\$4 therm\$4) with (melt\$4 vapor\$6 evaporat\$4 decompos\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 16:17 |
| S26 | 55 | S24 and (organic with (temperatur\$4 heat\$4 therm\$4) with (remov\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 16:34 |
| S27 | 78 | S25 not S26 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 16:20 |
| S28 | 89 | S22 and (organic with (temperatur\$4 heat\$4 therm\$4) with (remov\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 16:36 |
| S29 | 34 | S28 not S26 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/09/26 16:58 |
| S30 | 7 | ("6033977" "6174804" "6284641" "6309957").PN. OR ("6440842").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/05/28 20:34 |
| S31 | 21 | ("5512514" "5691238" "5693568" "5705430" "5795823" "5981374" "6187663").PN. OR ("6309957").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/05/28 20:35 |
| S32 | 13 | ("20020028575" "20020098677" "20030064577" "20040063305" "20050037604" "5798559" "6255712" "6440838" "6440861" "6780753" "6815329" "6841844").PN. OR ("6949456").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/05/28 20:37 |
| S33 | 67 | ("4523372" "5158910" "5422309" "5529953" "5602423" "5614765" "5705430" "5710061" "5801099").PN. OR ("6033977").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2007/05/28 20:43 |
| S34 | 3956 | ((dielectric insulat\$3) with organic) and (decomposit\$3 with (thermal\$3 heat\$3 temperatur\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:20 |
| S35 | 1772 | S34 and ((dielectric insulat\$3 organic) with (decomposit\$3 with (thermal\$3 heat\$3 temperatur\$3))) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:25 |

EAST Search History

| | | | | | | |
|-----|------|--|---|----|----|------------------|
| S36 | 1449 | S35 and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615") | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:40 |
| S37 | 780 | S36 and (trench recess\$3 groov\$3 open\$3 plug) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:15 |
| S38 | 418 | S37 and semiconduct\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:22 |
| S39 | 18 | (US-20060128089-\$ or US-20050179135-\$ or US-20050124168-\$ or US-20050151256-\$ or US-20050079705-\$).did. or (US-6309957-\$ or US-6821896-\$ or US-6174804-\$ or US-6033977-\$ or US-6440842-\$ or US-6949456-\$ or US-6358849-\$ or US-6803669-\$ or US-6898851-\$ or US-6800551-\$ or US-6664181-\$ or US-6440838-\$ or US-6514671-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/05/30 15:22 |
| S40 | 415 | S38 not S39 | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:23 |
| S41 | 219 | S40 and (photoresist \$4resist photomask photo-resist photo-mask) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:23 |
| S42 | 212 | S41 and (trench recess\$3 groov\$3 open\$3) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:24 |
| S43 | 200 | S42 and (decomposit\$3 near5 (thermal\$3 heat\$3 temperatur\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:25 |
| S44 | 212 | S42 and ((organic dielectric insulat\$3) with decomposit\$3 with (thermal\$3 heat\$3 temperatur\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:26 |
| S45 | 200 | S43 and ((organic dielectric insulat\$3) with decomposit\$3 with (thermal\$3 heat\$3 temperatur\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:27 |
| S46 | 198 | S45 and (substrate wafer) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:27 |
| S47 | 135 | S46 and liquid | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 15:27 |
| S48 | 92 | S47 and (solid\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:39 |

EAST Search History

| | | | | | | |
|-----|----|--|---|----|----|------------------|
| S49 | 92 | (US-20020189495-\$ or US-20030196680-\$ or US-20040163758-\$ or US-20070102685-\$ or US-20070102684-\$ or US-20070102683-\$ or US-20070102682-\$ or US-20070102681-\$ or US-20070102680-\$ or US-20070102679-\$ or US-20070102678-\$ or US-20070102677-\$ or US-20070096065-\$ or US-20070096064-\$ or US-20070096063-\$ or US-20070096062-\$ or US-20060043346-\$ or US-20030205817-\$ or US-20040169287-\$ or US-20010026021-\$ or US-20070019028-\$ or US-20050057908-\$ or US-20030147227-\$ or US-20050129383-\$ or US-20050047927-\$ or US-20030198578-\$).did. or (US-20030180451-\$ or US-20030148024-\$ or US-20030108664-\$ or US-20070104870-\$ or US-20070104869-\$ or US-20070104882-\$ or US-20070104881-\$ or US-20070104880-\$ or US-20070104879-\$ or US-20070104876-\$ or US-20070104875-\$ or US-20070104883-\$ or US-20030124259-\$ or US-20030087036-\$ or US-20030175411-\$ or US-20020018845-\$ or US-20020176927-\$ or US-20030099844-\$ or US-20020102501-\$ or US-20070117271-\$ or US-20030092213-\$ or US-20050272248-\$ or US-20040102031-\$ or US-20050032357-\$ or US-20070099330-\$ or US-20050255710-\$ or US-20030004218-\$).did. or (US-5534069-\$ or US-6113730-\$ or US-5686172-\$ or US-6046410-\$ or US-5393406-\$ or US-5622634-\$ or US-6072207-\$ or US-6492659-\$ or US-5900674-\$ or US-6734566-\$ or US-6298551-\$ or US-6826830-\$ or US-6366015-\$ or US-7122152-\$ or US-5547708-\$ or US-6951666-\$ or US-6800330-\$ or US-6787191-\$ or US-6946159-\$ or US-6506440-\$ or US-6296896-\$ or US-6998148-\$ or US-6685983-\$ or US-6887332-\$ or US-6379745-\$ or US-5830548-\$).did. or (US-6338936-\$ or US-6576409-\$ or US-6077635-\$ or US-7074650-\$ or US-6762081-\$ or US-6596624-\$ or US-5953634-\$ or US-6156657-\$ or US-6602804-\$ or US-5602060-\$ or US-6334803-\$ or US-6420441-\$ or US-6232386-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/05/30 18:39 |
| S50 | 1 | ((thermal near2 decompost\$4) with (polymer\$3 polyimide)) and (insulat\$4 dielectric) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615") | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:41 |
| S51 | 21 | (US-20060128089-\$ or US-20050179135-\$ or US-20050124168-\$ or US-20050151256-\$ or US-20050079705-\$ or US-20050272248-\$ or US-20030205817-\$).did. or (US-6309957-\$ or US-6821896-\$ or US-6174804-\$ or US-6033977-\$ or US-6440842-\$ or US-6949456-\$ or US-6358849-\$ or US-6803669-\$ or US-6898851-\$ or US-6800551-\$ or US-6664181-\$ or US-6440838-\$ or US-6514671-\$ or US-6596624-\$).did. | US-PGPUB; USPAT | OR | ON | 2007/05/30 18:40 |
| S52 | 1 | ((thermal\$3 near2 decompost\$4) with (polymer\$3 polyimide)) and (insulat\$4 dielectric) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615") | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:42 |
| S53 | 7 | ((thermal\$3 near2 decompost\$4) with (polymer\$3 polyimide)) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615") | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:42 |
| S54 | 11 | ((thermal\$3 near2 decompost\$4) same (polymer\$3 polyimide)) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615") | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:44 |

EAST Search History

| | | | | | | |
|-----|-------|--|---|----|-----|------------------|
| S55 | 56 | ((thermal\$3 near2 decompost\$4)) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615") | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:46 |
| S56 | 45 | S55 not (S49 S51 S54) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:47 |
| S57 | 25 | S56 and organic | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:44 |
| S58 | 140 | ((((temperat\$4 heat\$3 thermal\$3) near4 decompost\$4)) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615") | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:51 |
| S59 | 0 | S58 not (S49 S51 S54 S58) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:47 |
| S60 | 104 | S58 not (S49 S51 S54 S57) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:51 |
| S61 | 44 | S60 and organic | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:47 |
| S62 | 23218 | (organic with decomposit\$4) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615") | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:09 |
| S63 | 23128 | S62 not (S49 S51 S54 S57 S58) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:51 |
| S64 | 5715 | S63 and (insulat\$4 dielectric) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:09 |
| S65 | 2 | S64 and ((temperat\$4 heat\$3 thermal\$3) with decompost\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:11 |
| S66 | 10 | S64 and ((temperat\$4 heat\$3 thermal\$3) same decompost\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 18:58 |
| S67 | 1 | ("6141072").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | OFF | 2007/05/30 18:59 |

EAST Search History

| | | | | | | |
|-----|-------|--|---|----|-----|------------------|
| S68 | 1 | ("6165890").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | OFF | 2007/05/30 19:00 |
| S69 | 1 | ("7141885").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | OFF | 2007/05/30 19:08 |
| S70 | 12607 | (organic and (remov\$4 with decompos\$4)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:14 |
| S71 | 10992 | (S70 not (S49 S51 S54 S57 S58 S66)) and (@ad<"20021220" @rlad<"20021220" @pd<"20040615" @rlpd<"20040615") | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:09 |
| S72 | 930 | S71 and (insulat\$4 dielectric) and semiconduct\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:09 |
| S74 | 375 | S72 and ((temperat\$4 heat\$3 thermal\$3) with decomposit\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:10 |
| S75 | 3884 | S64 and ((temperat\$4 heat\$3 thermal\$3) with decomposit\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:12 |
| S76 | 3102 | (S74 S75) and ((temperat\$4 heat\$3 thermal\$3) with decomposit\$4 with organic) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:13 |
| S77 | 973 | S76 and semiconductor | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:13 |
| S78 | 78 | S77 and (remov\$4 with decompos\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:14 |
| S79 | 147 | S77 and (remov\$4 with decomposit\$4) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:14 |
| S80 | 98 | S79 and (trench recess\$3 groov\$3 open\$3 plug) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 22:42 |
| S81 | 91 | S80 and (substrate wafer) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/05/30 19:16 |

EAST Search History

| | | | | | | |
|-----|-------|--|---|----|----|------------------|
| S82 | 20381 | 438/618,622,633,637,638,692,552,662,663,672,675,677,698,679,700,704-706,714,725.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:11 |
| S83 | 910 | S82 and ((therm\$4 temperatur\$3 heat\$3) with (decompo\$4 destro\$3 wast\$3 consum\$3 absorb\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:30 |
| S84 | 673 | S83 and (embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:31 |
| S85 | 427 | S83 and (embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:31 |
| S86 | 274 | S85 and ((therm\$4 temperatur\$3 heat\$3) with (remov\$3 wast\$3 etch\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:32 |
| S87 | 152 | S86 and ((therm\$4 temperatur\$3 heat\$3) near\$3 (decompo\$4 destro\$3 wast\$3 consum\$3 absorb\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:22 |
| S88 | 9 | S87 and ((therm\$4 temperatur\$3 heat\$3) near\$3 (decompo\$4 destro\$3 wast\$3 consum\$3 absorb\$3)).ab. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:24 |
| S89 | 0 | S87 and ((therm\$4 temperatur\$3 heat\$3) near\$3 (decompo\$4 destro\$3 wast\$3 consum\$3 absorb\$3)).ti. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:25 |
| S90 | 22 | S87 and ((therm\$4 temperatur\$3 heat\$3) near\$3 (decompo\$4 destro\$3 wast\$3 consum\$3 absorb\$3)).clm. | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:29 |
| S91 | 129 | S87 not (S88 S90) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:33 |
| S92 | 1237 | S82 and ((therm\$4 temperatur\$3 heat\$3) with (decompo\$4 decomposit\$3 destro\$3 wast\$3 consum\$3 absorb\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:48 |
| S93 | 958 | S92 and (embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 13:46 |
| S94 | 616 | S93 and (embed\$3 encav\$3 enclos\$3 cover\$3 recess\$3 buried) with (dielectric insulat\$3 organic \$3oxid\$3 nitrid\$3 interlayer interdielectric interinsulat\$3 (inter adj layer) (inter adj dielectric) (inter adj insulat\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 13:49 |

EAST Search History

| | | | | | | |
|-----|------|---|---|----|----|------------------|
| S95 | 385 | S94 and ((therm\$4 temperatur\$3 heat\$3) with (remov\$3 wast\$3 etch\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:33 |
| S96 | 362 | (S91 S95) not (S88 S90) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:33 |
| S97 | 1243 | S82 and ((therm\$4 temperatur\$3 heat\$3) with (decompos\$4 decomposit\$3 destro\$3 wast\$3 consum\$3 absorb\$3)) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/27 13:46 |
| S98 | 368 | (S97 not S92) S96 | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2007/09/26 19:53 |